

# 74F37

## Quad Two-Input NAND Buffer

### General Description

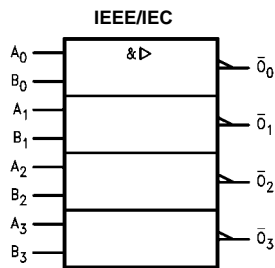
This device contains four independent gates, each of which performs the logic NAND function.

### Ordering Code:

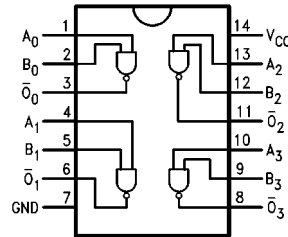
Order Number	Package Number	Package Description
74F37SC	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150 Narrow
74F37SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F37PC	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

### Logic Symbol



### Connection Diagram



### Unit Loading/Fan Out

Pin Names	Description	U.L.	Input $I_{IH}/I_{IL}$
		HIGH/LOW	Output $I_{OH}/I_{OL}$
$A_n, B_n$	Inputs	1.0/2.0	20 $\mu$ A/-1.2 mA
$\bar{O}_n$	Outputs	600/106.6 (80)	-12 mA/64 mA (48 mA)

### Function Table

Inputs		Output
A	B	$\bar{O}$
L	L	H
L	H	H
H	L	H
H	H	L

H = HIGH Voltage Level  
L = LOW Voltage Level

**Absolute Maximum Ratings** (Note 1)

Storage Temperature	-65°C to +150°C
Ambient Temperature under Bias	-55°C to +125°C
Junction Temperature under Bias	-55°C to +150°C
V <sub>CC</sub> Pin Potential to Ground Pin	-0.5V to +7.0V
Input Voltage (Note 2)	-0.5V to +7.0V
Input Current (Note 2)	-30 mA to +5.0 mA
Voltage Applied to Output in HIGH State (with V <sub>CC</sub> = 0V)	
Standard Output	-0.5V to V <sub>CC</sub>
3-STATE Output	-0.5V to +5.5V
Current Applied to Output in LOW State (Max)	twice the rated I <sub>OL</sub> (mA)

**Recommended Operating Conditions**

Free Air Ambient Temperature	0°C to +70°C
Supply Voltage	+4.5V to +5.5V

**Note 1:** Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

**Note 2:** Either voltage limit or current limit is sufficient to protect inputs.

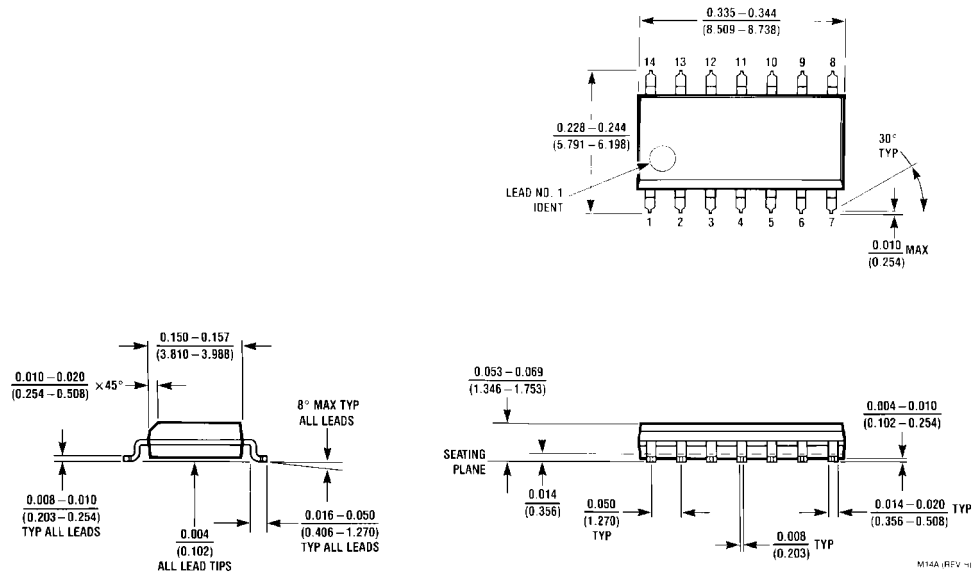
**DC Electrical Characteristics**

Symbol	Parameter	Min	Typ	Max	Units	V <sub>CC</sub>	Conditions
V <sub>IH</sub>	Input HIGH Voltage	2.0			V		Recognized as a HIGH Signal
V <sub>IL</sub>	Input LOW Voltage			0.8	V		Recognized as a LOW Signal
V <sub>CD</sub>	Input Clamp Diode Voltage			-1.2	V	Min	I <sub>IN</sub> = -18 mA
V <sub>OH</sub>	Output HIGH Voltage	10% V <sub>CC</sub> 10% V <sub>CC</sub> 5% V <sub>CC</sub>	2.4 2.0 2.7		V	Min	I <sub>OH</sub> = -3 mA I <sub>OH</sub> = -15 mA I <sub>OH</sub> = -3 mA
V <sub>OL</sub>	Output LOW Voltage	10% V <sub>CC</sub>		0.55	V	Min	I <sub>OL</sub> = 64 mA
I <sub>IH</sub>	Input HIGH Current			5.0	μA	Max	V <sub>IN</sub> = 2.7V
I <sub>BVI</sub>	Input HIGH Current Breakdown Test			7.0	μA	Max	V <sub>IN</sub> = 7.0V
I <sub>CEX</sub>	Output HIGH Leakage Current			50	μA	Max	V <sub>OUT</sub> = V <sub>CC</sub>
V <sub>ID</sub>	Input Leakage Test	4.75			V	0.0	I <sub>ID</sub> = 1.9 μA All Other Pins Grounded
I <sub>OD</sub>	Output Leakage Circuit Current			3.75	μA	0.0	V <sub>IOD</sub> = 150 mV All Other Pins Grounded
I <sub>IL</sub>	Input LOW Current			-1.2	mA	Max	V <sub>IN</sub> = 0.5V
I <sub>OS</sub>	Output Short-Circuit Current	-100		-225	mA	Max	V <sub>OUT</sub> = 0V
I <sub>CCH</sub>	Power Supply Current		3.7	6.0	mA	Max	V <sub>O</sub> = HIGH
I <sub>CCL</sub>	Power Supply Current		28.0	33.0	mA	Max	V <sub>O</sub> = LOW

**AC Electrical Characteristics**

Symbol	Parameter	T <sub>A</sub> = +25°C V <sub>CC</sub> = +5.0V C <sub>L</sub> = 50 pF			T <sub>A</sub> = 0°C to +70°C C <sub>L</sub> = 50 pF		Units
		Min	Typ	Max	Min	Max	
t <sub>PLH</sub>	Propagation Delay	2.0	3.2	5.5	1.5	6.5	ns
t <sub>PHL</sub>	A <sub>n</sub> , B <sub>n</sub> to $\bar{O}_n$	1.5	2.4	4.5	1.0	5.0	

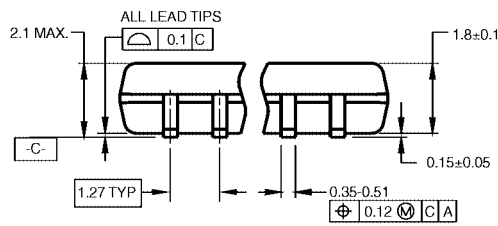
**Physical Dimensions** inches (millimeters) unless otherwise noted



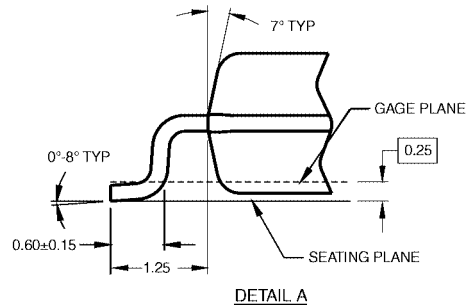
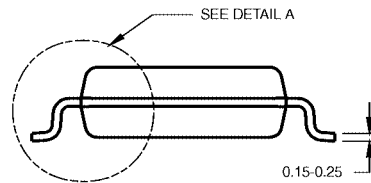
**14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150 Narrow Package Number M14A**

M14A (REV. 1)

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



DIMENSIONS ARE IN MILLIMETERS

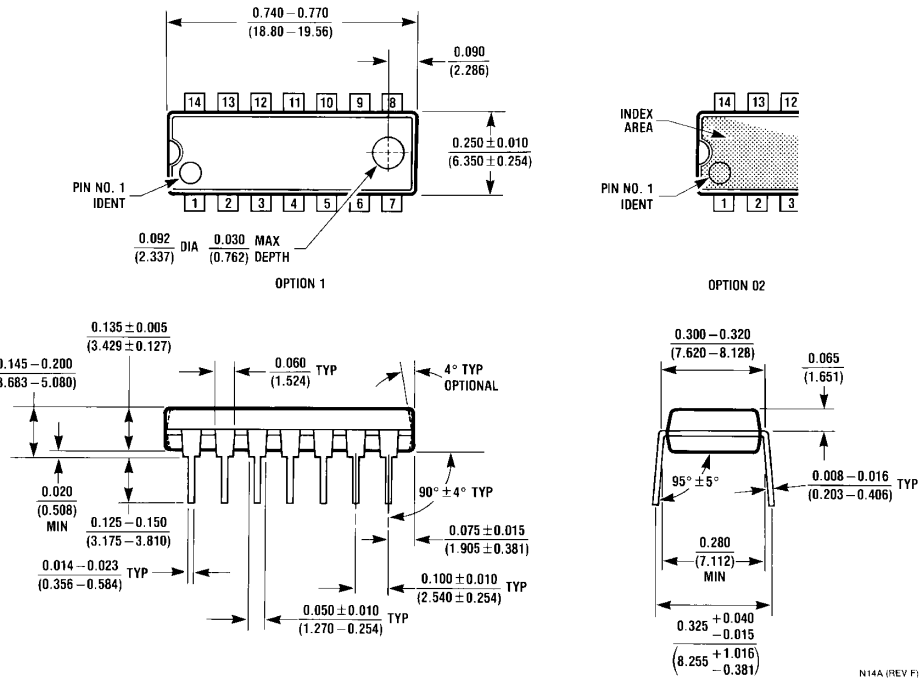


- NOTES:
- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
  - B. DIMENSIONS ARE IN MILLIMETERS.
  - C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M14DRevB1

**14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide  
Package Number M14D**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



**14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide Package Number N14A**

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